



# RF Power Field Effect Transistors

## N-Channel Enhancement-Mode Lateral MOSFETs

Designed for GSM and EDGE base station applications with frequencies from 1800 to 2000 MHz. Suitable for FM, TDMA, CDMA and multicarrier amplifier applications. Specified for GSM 1930-1990 MHz.

- Typical GSM Performance:  
 Power Gain - 14 dB (Typ) @ 30 Watts  
 Efficiency - 50% (Typ) @ 30 Watts
- Capable of Handling 5:1 VSWR, @ 26 Vdc, 30 Watts CW Output Power

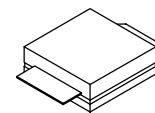
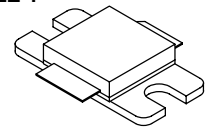
### Features

- Internally Matched for Ease of Use
- High Gain, High Efficiency and High Linearity
- Integrated ESD Protection
- Designed for Maximum Gain and Insertion Phase Flatness
- Excellent Thermal Stability
- Low Gold Plating Thickness on Leads, 40μm Nominal.
- RoHS Compliant
- In Tape and Reel. R3 Suffix = 250 Units per 32 mm, 13 inch Reel.

**MRF18030BLR3**  
**MRF18030BLSR3**

**1930-1990 MHz, 30 W, 26 V**  
**GSM/GSM EDGE**  
**LATERAL N-CHANNEL**  
**RF POWER MOSFETs**

**CASE 465E-04, STYLE 1**  
**NI-400**  
**MRF18030BLR3**



**CASE 465F-04, STYLE 1**  
**NI-400S**  
**MRF18030BLSR3**

**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	- 0.5, +65	Vdc
Gate-Source Voltage	$V_{GS}$	- 0.5, +15	Vdc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	83.3 0.48	W W/ $^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	- 65 to +150	$^\circ\text{C}$
Case Operating Temperature	$T_C$	150	$^\circ\text{C}$
Operating Junction Temperature	$T_J$	200	$^\circ\text{C}$

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.1	$^\circ\text{C}/\text{W}$

**Table 3. ESD Protection Characteristics**

Test Conditions	Class
Human Body Model	2 (Minimum)
Machine Model	M3 (Minimum)

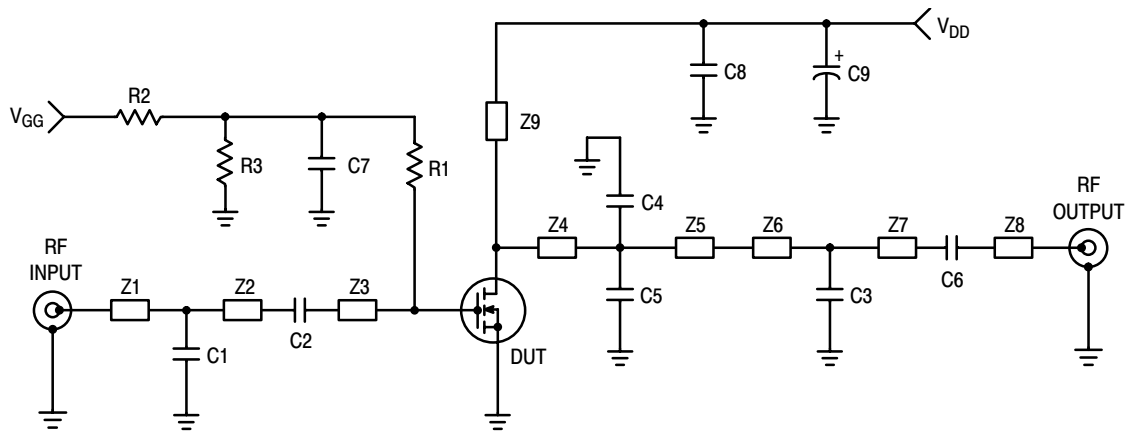
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**Table 4. Electrical Characteristics** ( $T_C = 25^\circ\text{C}$ , 50 ohm system unless otherwise noted)

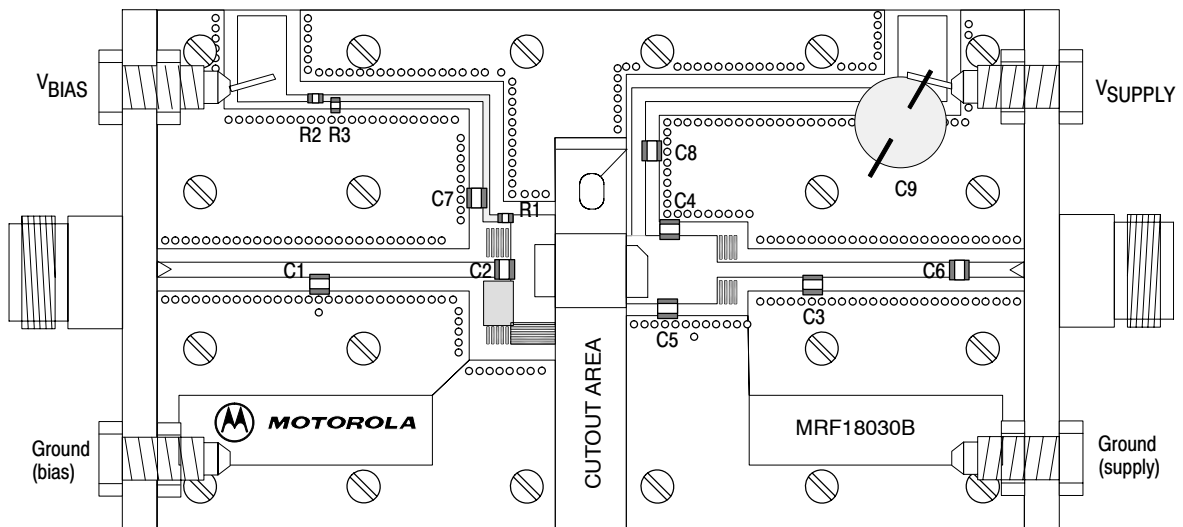
Characteristic	Symbol	Min	Typ	Max	Unit
<b>Off Characteristics</b>					
Drain-Source Breakdown Voltage ( $V_{GS} = 0 \text{ Vdc}$ , $I_D = 20 \mu\text{Adc}$ )	$V_{(BR)DSS}$	65	—	—	Vdc
Zero Gate Voltage Drain Current ( $V_{DS} = 26 \text{ Vdc}$ , $V_{GS} = 0 \text{ Vdc}$ )	$I_{DSS}$	—	—	1	$\mu\text{Adc}$
Gate-Source Leakage Current ( $V_{GS} = 5 \text{ Vdc}$ , $V_{DS} = 0 \text{ Vdc}$ )	$I_{GSS}$	—	—	1	$\mu\text{Adc}$
<b>On Characteristics</b>					
Gate Threshold Voltage ( $V_{DS} = 10 \text{ Vdc}$ , $I_D = 100 \mu\text{Adc}$ )	$V_{GS(th)}$	2	3	4	Vdc
Gate Quiescent Voltage ( $V_{DS} = 26 \text{ Vdc}$ , $I_D = 250 \text{ mAdc}$ )	$V_{GS(Q)}$	2	3.9	4.5	Vdc
Drain-Source On-Voltage ( $V_{GS} = 10 \text{ Vdc}$ , $I_D = 1 \text{ Adc}$ )	$V_{DS(on)}$	—	0.29	0.4	Vdc
Forward Transconductance ( $V_{DS} = 10 \text{ Vdc}$ , $I_D = 1 \text{ Adc}$ )	$g_{fs}$	—	2	—	S
<b>Dynamic Characteristics</b>					
Reverse Transfer Capacitance (1) ( $V_{DS} = 26 \text{ Vdc} \pm 30 \text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0 \text{ Vdc}$ )	$C_{rss}$	—	1.3	—	pF
<b>Functional Tests</b> (In Freescale Test Fixture) (2)					
Output Power, 1 dB Compression Point ( $V_{DD} = 26 \text{ Vdc}$ , $I_{DQ} = 250 \text{ mA}$ , $f = 1930 - 1990 \text{ MHz}$ )	P1dB	27	30	—	W
Common-Source Amplifier Power Gain @ 30 W ( $V_{DD} = 26 \text{ Vdc}$ , $I_{DQ} = 250 \text{ mA}$ , $f = 1930 - 1990 \text{ MHz}$ )	$G_{ps}$	13	14	—	dB
Drain Efficiency @ 30 W ( $V_{DD} = 26 \text{ Vdc}$ , $I_{DQ} = 250 \text{ mA}$ , $f = 1930 - 1990 \text{ MHz}$ )	$\eta$	46.5	50	—	%
Input Return Loss @ 30 W ( $V_{DD} = 26 \text{ Vdc}$ , $I_{DQ} = 250 \text{ mA}$ , $f = 1930 - 1990 \text{ MHz}$ )	IRL	—	-12	-9	dB

1. Part internally matched both on input and output.
2. Device specifications obtained on a Production Test Fixture.



C1	1.8 pF, 100B Chip Capacitor	Z2	1.022" x 0.087" Microstrip
C2	0.8 pF, 100B Chip Capacitor	Z3	0.257" x 0.633" Microstrip
C3	0.8 pF, 100B Chip Capacitor	Z4	0.189" x 0.394" Microstrip
C4, C5	1.2 pF, 100B Chip Capacitors	Z5	0.335" x 0.394" Microstrip
C6, C7, C8	8.2 pF, 100B Chip Capacitors	Z6	0.616" x 0.087" Microstrip
C9	220 $\mu$ F, 63 V Electrolytic Capacitor	Z7	0.845" x 0.087" Microstrip
R1	1.0 k $\Omega$ , 1/8 W Chip Resistor (0805)	Z8	0.366" x 0.087" Microstrip
R2, R3	10 k $\Omega$ , 1/8 W Chip Resistors (0805)	Z9	$\approx$ 0.500" x 0.087" Microstrip
Z1	0.496" x 0.087" Microstrip		

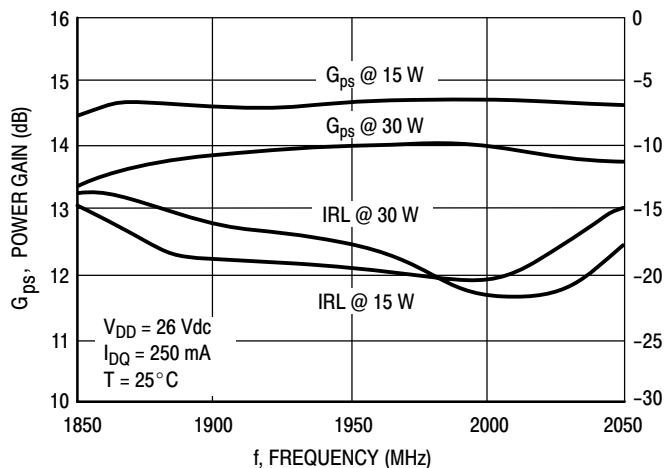
**Figure 1. 1930 - 1990 MHz Test Fixture Schematic**



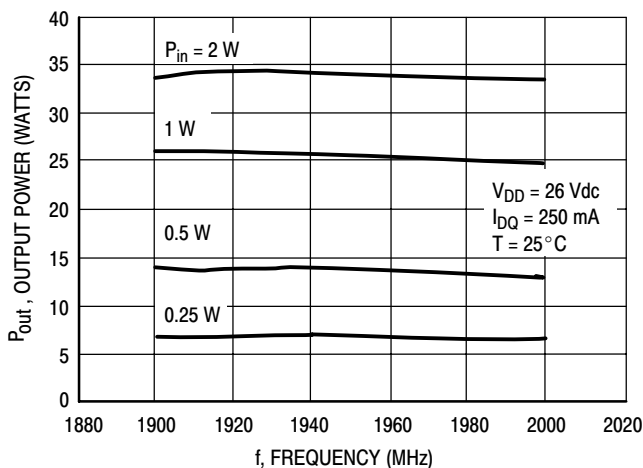
Freescale has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescale Semiconductor signature/logo. PCBs may have either Motorola or Freescale markings during the transition period. These changes will have no impact on form, fit or function of the current product.

**Figure 2. 1930 - 1990 MHz Test Fixture Component Layout**

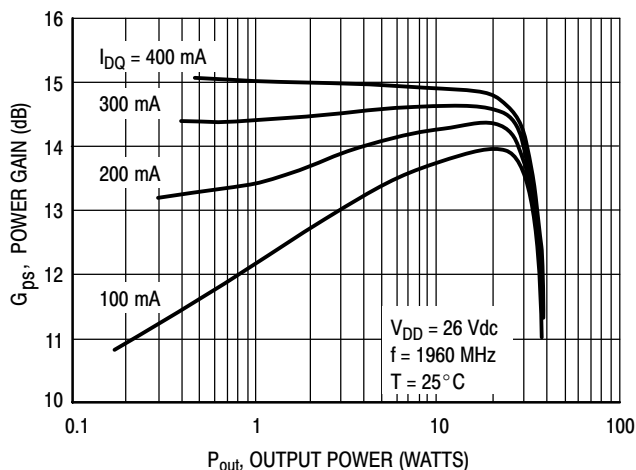
## TYPICAL CHARACTERISTICS



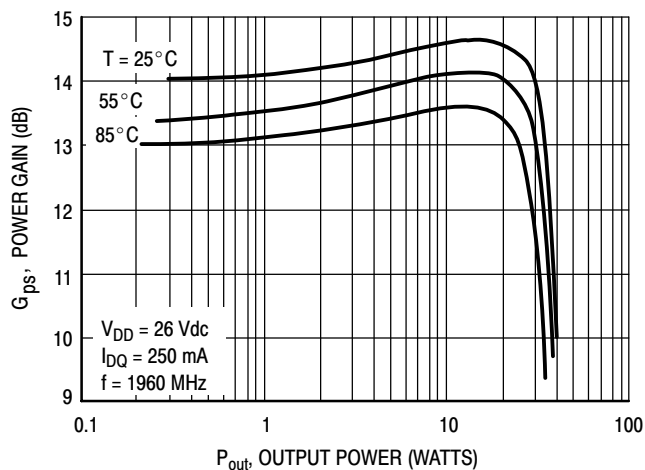
**Figure 3. Wideband Gain and IRL at 30 W and 15 W Output Power**



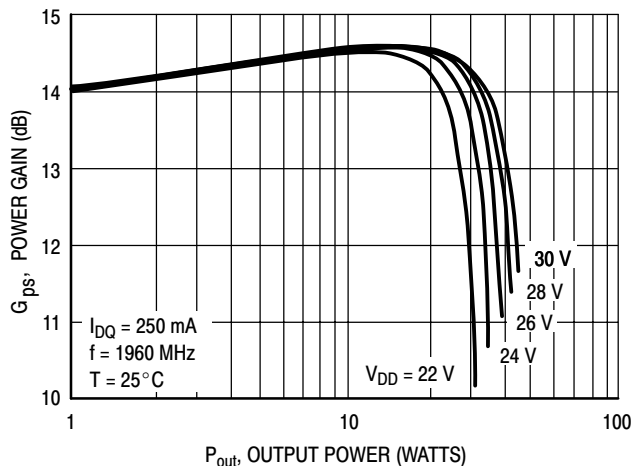
**Figure 4. Output Power versus Frequency**



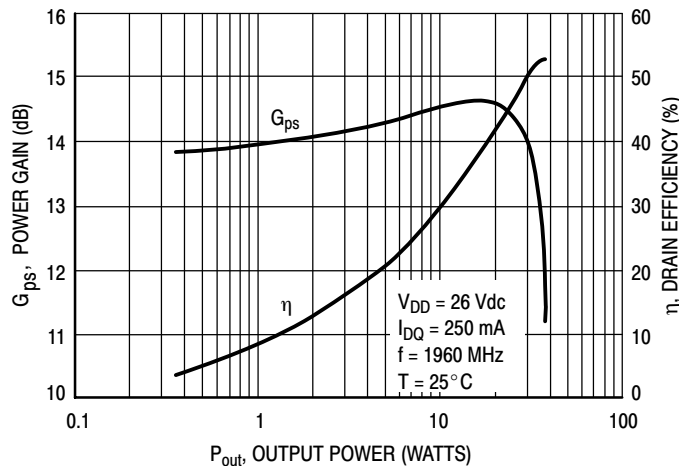
**Figure 5. Power Gain versus Output Power**



**Figure 6. Power Gain versus Output Power**



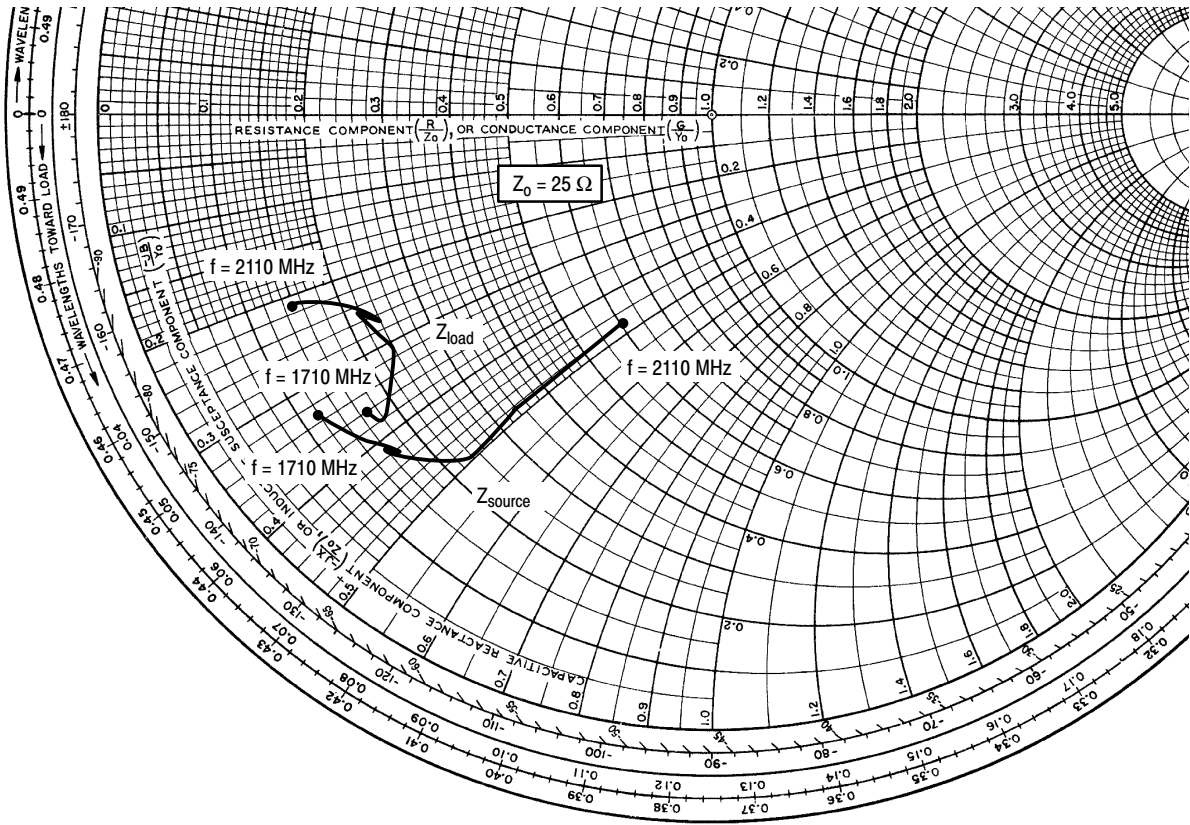
**Figure 7. Power Gain versus Output Power**



**Figure 8. Power Gain and Efficiency versus Output Power**

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$V_{DD} = 26\text{ V}$ ,  $I_{DQ} = 250\text{ mA}$ ,  $P_{out} = 30\text{ W (CW)}$

f MHz	$Z_{source}$ $\Omega$	$Z_{load}$ $\Omega$
1710	$2.92 - j8.24$	$4.18 - j9.06$
1785	$3.84 - j9.75$	$4.59 - j9.46$
1805	$4.15 - j10.38$	$4.98 - j9.06$
1840	$4.04 - j10.22$	$6.10 - j7.63$
1880	$6.12 - j12.29$	$5.83 - j6.89$
1960	$6.20 - j12.29$	$5.55 - j6.33$
1990	$8.61 - j12.10$	$5.93 - j6.66$
2110	$15.19 - j11.85$	$3.82 - j5.33$

$Z_{source}$  = Test circuit impedance as measured from gate to ground.

$Z_{load}$  = Test circuit impedance as measured from drain to ground.

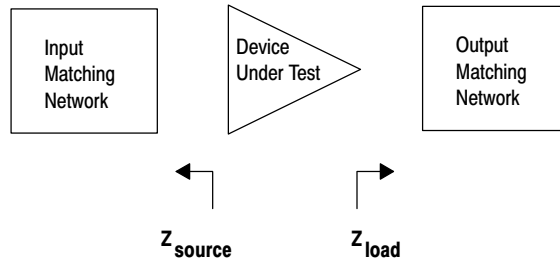


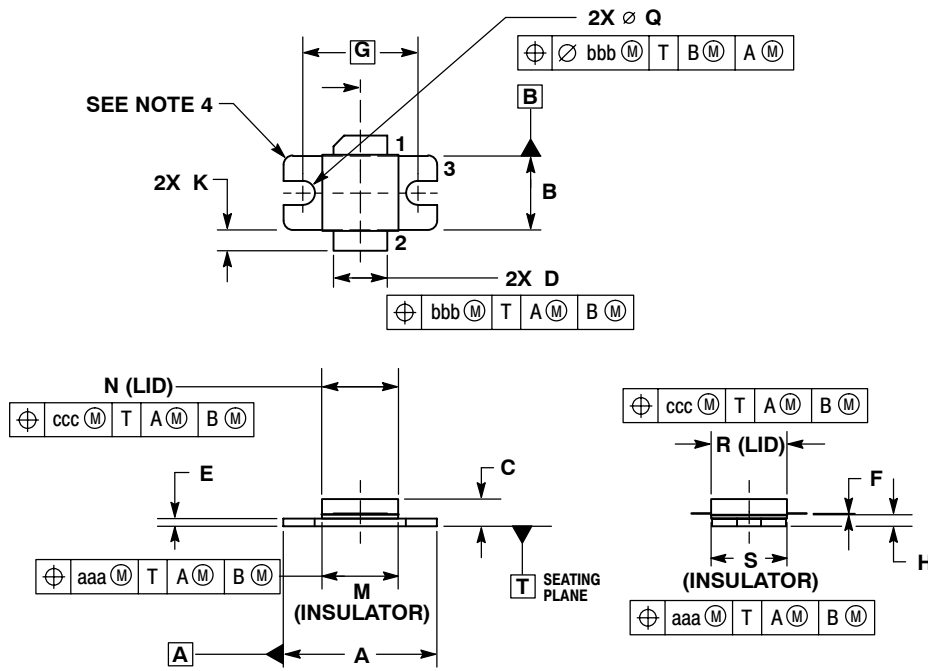
Figure 9. Series Equivalent Source and Load Impedance

# NOTES

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**PACKAGE DIMENSIONS**

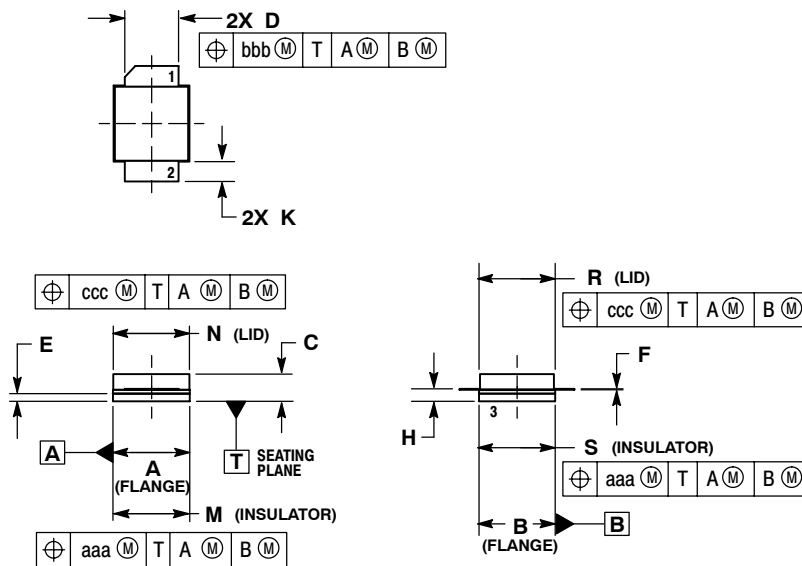


- NOTES:
1. CONTROLLING DIMENSION: INCH.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.
  4. INFORMATION ONLY: CORNER BREAK (4X) TO BE .060±.005 (1.52±0.13) RADIUS OR .06±.005 (1.52±0.13) x 45° CHAMFER.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.795	.805	20.19	20.44
B	.380	.390	9.65	9.9
C	.125	.163	3.17	4.14
D	.275	.285	6.98	7.24
E	.035	.045	0.89	1.14
F	.004	.006	0.10	0.15
G	.600 BSC		15.24 BSC	
H	.057	.067	1.45	1.7
K	.092	.122	2.33	3.1
M	.395	.405	10	10.3
N	.395	.405	10	10.3
Q	$\varnothing$ .120	$\varnothing$ .130	$\varnothing$ 3.05	$\varnothing$ 3.3
R	.395	.405	10	10.3
S	.395	.405	10	10.3
aaa	.005 BSC		0.127 BSC	
bbb	.010 BSC		0.254 BSC	
ccc	.015 BSC		0.381 BSC	

- STYLE 1:
1. DRAIN
  2. GATE
  3. SOURCE

**CASE 465E-04  
ISSUE F  
NI-400  
MRF18030BLR3**



- NOTES:
1. CONTROLLING DIMENSION: INCH.
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  3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.395	.405	10.03	10.29
B	.395	.405	10.03	10.29
C	.125	.163	3.18	4.14
D	.275	.285	6.98	7.24
E	.035	.045	0.89	1.14
F	.004	.006	0.10	0.15
H	.057	.067	1.45	1.70
K	.092	.122	2.34	3.10
M	.395	.405	10.03	10.29
N	.395	.405	10.03	10.29
R	.395	.405	10.03	10.29
S	.395	.405	10.03	10.29
aaa	.005 REF		0.127 REF	
bbb	.010 REF		0.254 REF	
ccc	.015 REF		0.38 REF	

- STYLE 1:
1. DRAIN
  2. GATE
  3. SOURCE

**CASE 465F-04  
ISSUE E  
NI-400S  
MRF18030BLSR3**

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